



# STGW30NB60H

## N-CHANNEL 30A - 600V TO-247 PowerMESH™ IGBT

TYPE	V <sub>CES</sub>	V <sub>CE(sat)</sub>	I <sub>C</sub>
STGW30NB60H	600 V	< 2.8 V	30 A

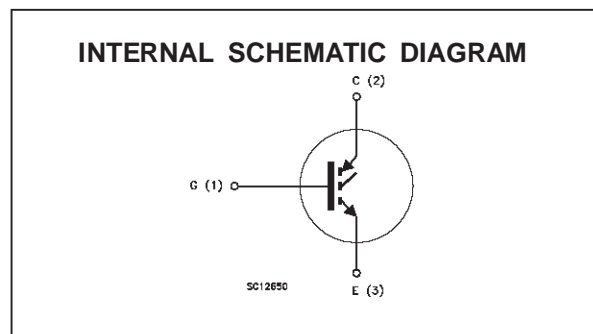
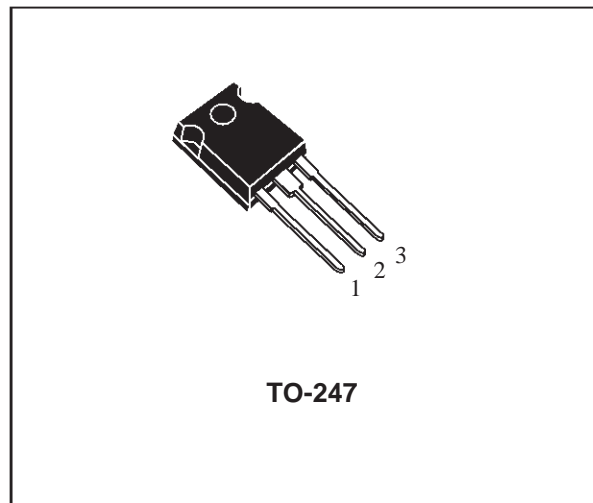
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (V<sub>CESAT</sub>)
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- VERY HIGH FREQUENCY OPERATION
- OFF LOSSES INCLUDE TAIL CURRENT

### DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "H" identifies a family optimized to achieve very low switching times for high frequency applications (<120kHz).

### APPLICATIONS

- HIGH FREQUENCY MOTOR CONTROLS
- WELDING EQUIPMENTS
- SMPS AND PFC IN BOTH HARD SWITCH AND RESONANT TOPOLOGIES



### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>GS</sub> = 0)	600	V
V <sub>ECR</sub>	Emitter-Collector Voltage	20	V
V <sub>GE</sub>	Gate-Emitter Voltage	± 20	V
I <sub>C</sub>	Collector Current (continuous) at T <sub>c</sub> = 25 °C	60	A
I <sub>C</sub>	Collector Current (continuous) at T <sub>c</sub> = 100 °C	30	A
I <sub>CM</sub> (•)	Collector Current (pulsed)	240	A
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	190	W
	Derating Factor	1.52	W/°C
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
T <sub>j</sub>	Max. Operating Junction Temperature	150	°C

(•) Pulse width limited by safe operating area

## STGW30NB60H

### THERMAL DATA

$R_{thj-case}$	Thermal Resistance Junction-case	Max	0.66	$^{\circ}C/W$
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Max	30	$^{\circ}C/W$
$R_{thc-h}$	Thermal Resistance Case- heatsink	Typ	0.1	$^{\circ}C/W$

### ELECTRICAL CHARACTERISTICS ( $T_j = 25^{\circ}C$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{BR(CEs)}$	Collector-Emitter Breakdown Voltage	$I_C = 250 \mu A$ $V_{GE} = 0$	600			V
$I_{CES}$	Collector cut-off ( $V_{GE} = 0$ )	$V_{CE} = \text{Max Rating}$ $T_j = 25^{\circ}C$ $V_{CE} = \text{Max Rating}$ $T_j = 125^{\circ}C$			10 100	$\mu A$ $\mu A$
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20 V$ $V_{CE} = 0$			$\pm 100$	nA

ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}$ $I_C = 250 \mu A$	3		5	V
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15 V$ $I_C = 30 A$ $V_{GE} = 15 V$ $I_C = 30 A$ $T_j = 125^{\circ}C$		2.2 1.8	2.8	V V

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}$	Forward Transconductance	$V_{CE} = 25 V$ $I_C = 30 A$		20		S
$C_{ies}$ $C_{oes}$ $C_{res}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{CE} = 25 V$ $f = 1 MHz$ $V_{GE} = 0$		2300 250 60		pF pF pF
$Q_G$ $Q_{GE}$ $Q_{GC}$	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	$V_{CE} = 480 V$ $I_C = 30 A$ $V_{GE} = 15 V$		150 15 72		nC nC nC
$I_{CL}$	Latching Current	$V_{clamp} = 480 V$ $R_G = 10 \Omega$ $T_j = 150^{\circ}C$	120			A

### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$	Delay Time Rise Time	$V_{CC} = 480 V$ $I_C = 30 A$ $V_{GE} = 15 V$ $R_G = 10 \Omega$		15 75		ns ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{CC} = 480 V$ $I_C = 30 A$ $R_G = 10 \Omega$ $V_{GE} = 15 V$		760		A/ $\mu s$
$E_{on}$	Turn-on Switching Losses	$T_j = 125^{\circ}C$		850		$\mu J$

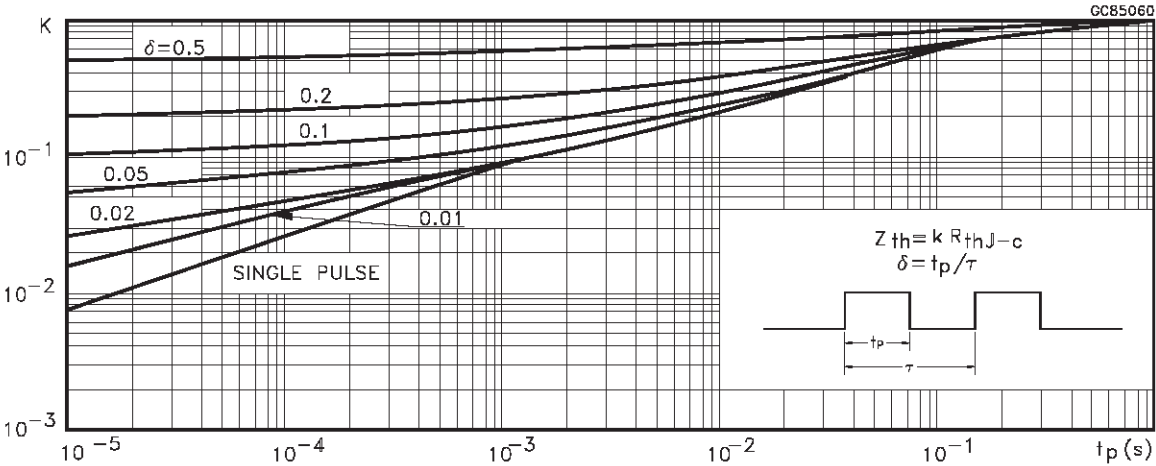
**ELECTRICAL CHARACTERISTICS** (continued)

**SWITCHING OFF**

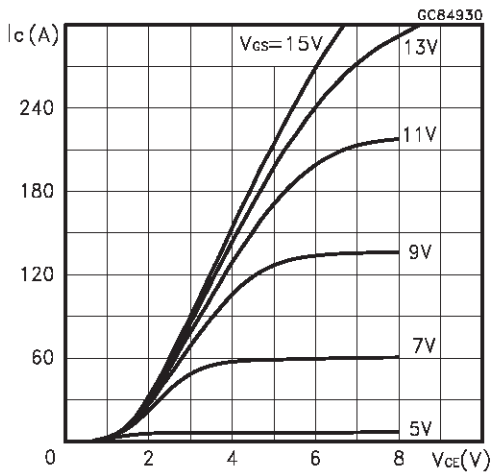
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_c$	Cross-Over Time	$V_{CC} = 480\text{ V}$		150		ns
$t_r(V_{off})$	Off Voltage Rise Time	$I_C = 30\text{ A}$ $R_{GE} = 10\ \Omega$		40		ns
$t_{d(off)}$	Delay Time	$V_{GE} = 15\text{ V}$		210		ns
$t_f$	Fall Time			90		ns
$E_{off(**)}$	Turn-off Switching Loss			1.10		mJ
$E_{ts}$	Total Switching Loss			1.8		mJ
$t_c$	Cross-Over Time	$V_{CC} = 480\text{ V}$		250		ns
$t_r(V_{off})$	Off Voltage Rise Time	$I_C = 30\text{ A}$ $R_{GE} = 10\ \Omega$		70		ns
$t_{d(off)}$	Delay Time	$V_{GE} = 15\text{ V}$ $T_j = 125\text{ }^\circ\text{C}$		250		ns
$t_f$	Fall Time			160		ns
$E_{off(**)}$	Turn-off Switching Loss			1.6		mJ
$E_{ts}$	Total Switching Loss			2.45		mJ

(\*) Pulse width limited by max. junction temperature  
 (\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %  
 (\*\*) Losses Include Also The Tail (Jedec Standardization)

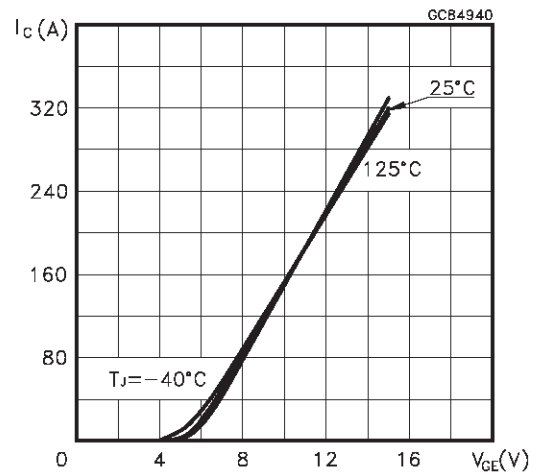
**Thermal Impedance**



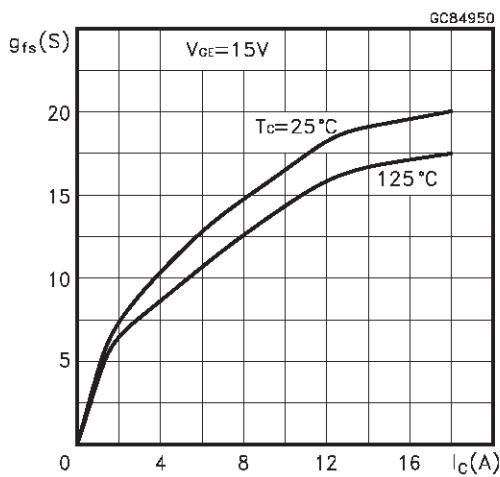
Output Characteristics



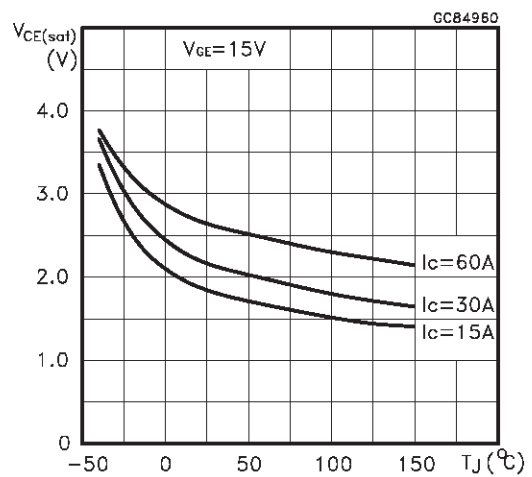
Transfer Characteristics



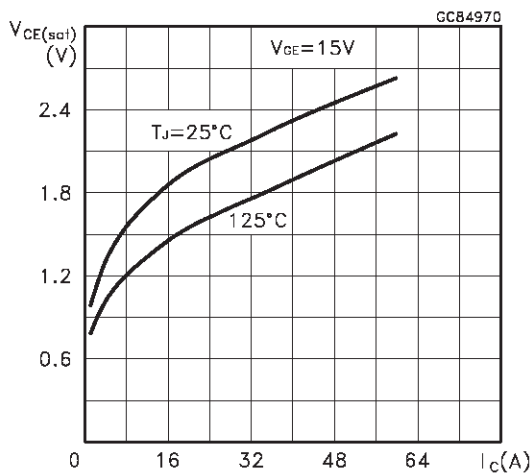
Transconductance



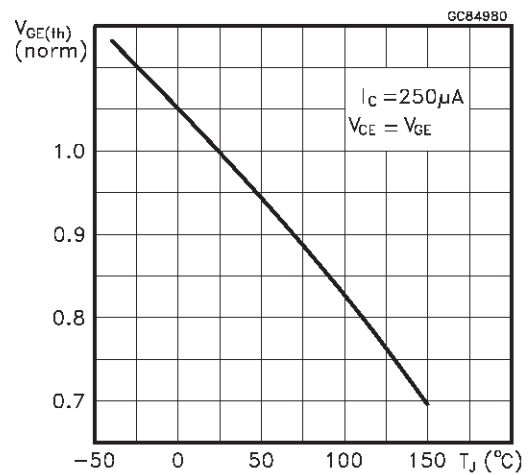
Collector-Emitter On Voltage vs Temperature



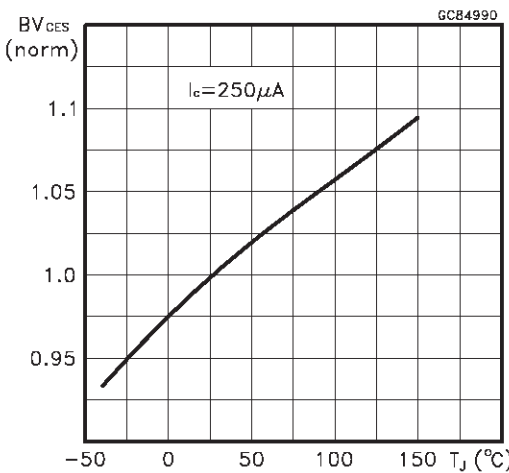
Collector-Emitter On Voltage vs Collector Current



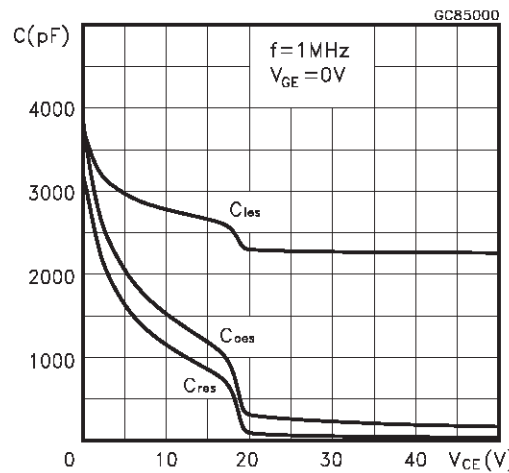
Gate Threshold vs Temperature



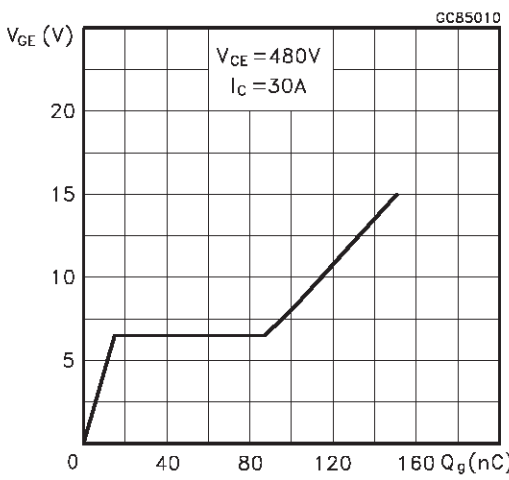
Normalized Breakdown Voltage vs Temperature



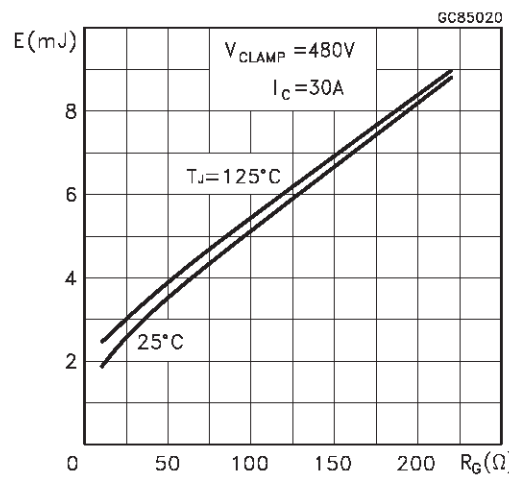
Capacitance Variations



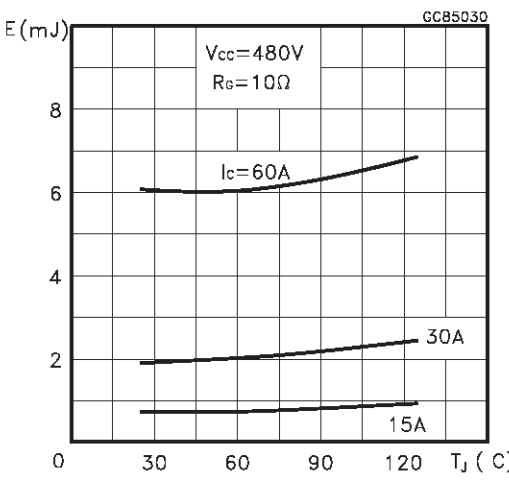
Gate Charge vs Gate-Emitter Voltage



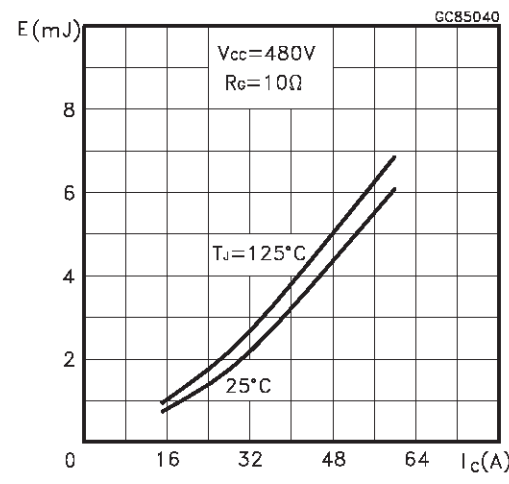
Total Switching Losses vs Gate Resistance



Total Switching Losses vs Temperature



Total Switching Losses vs Collector Current



Switching Off Safe Operating Area

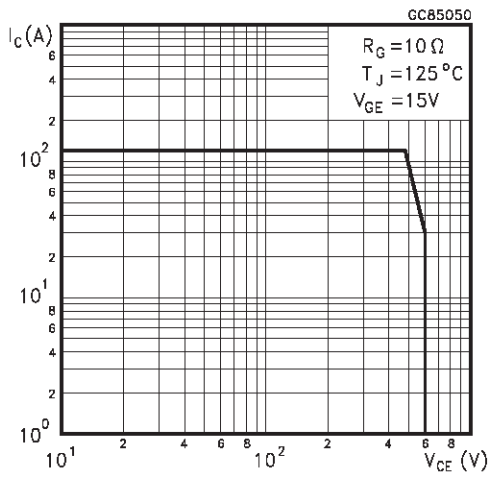


Fig. 1: Gate Charge test Circuit

Fig. 2: Test Circuit For Inductive Load Switching

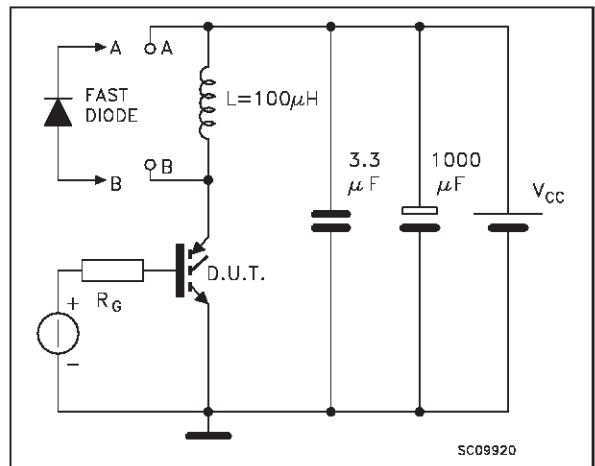
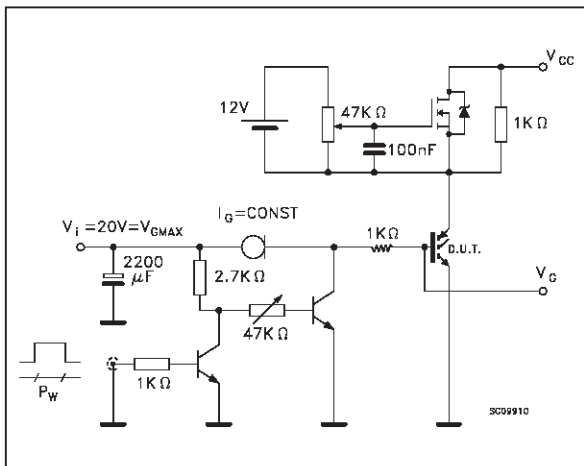
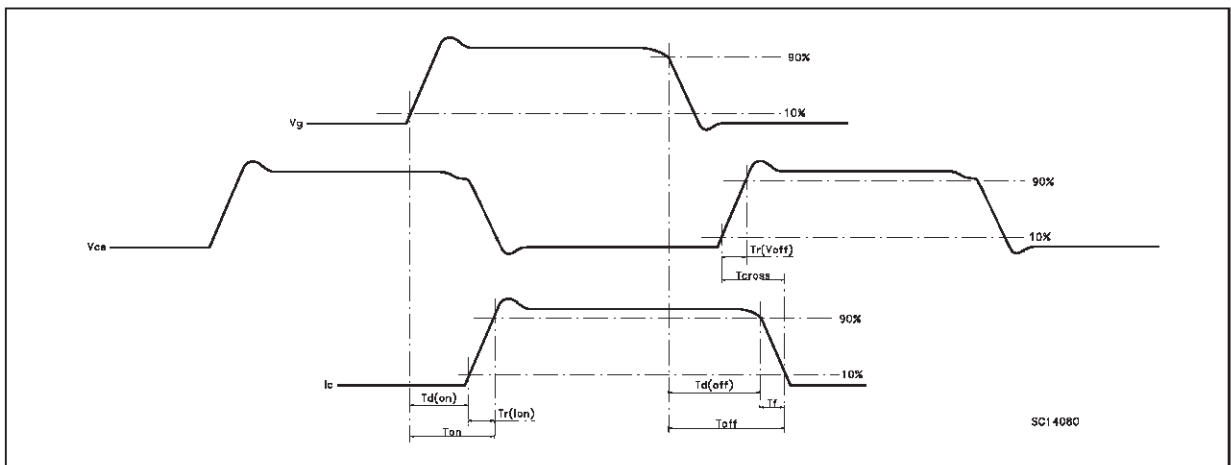
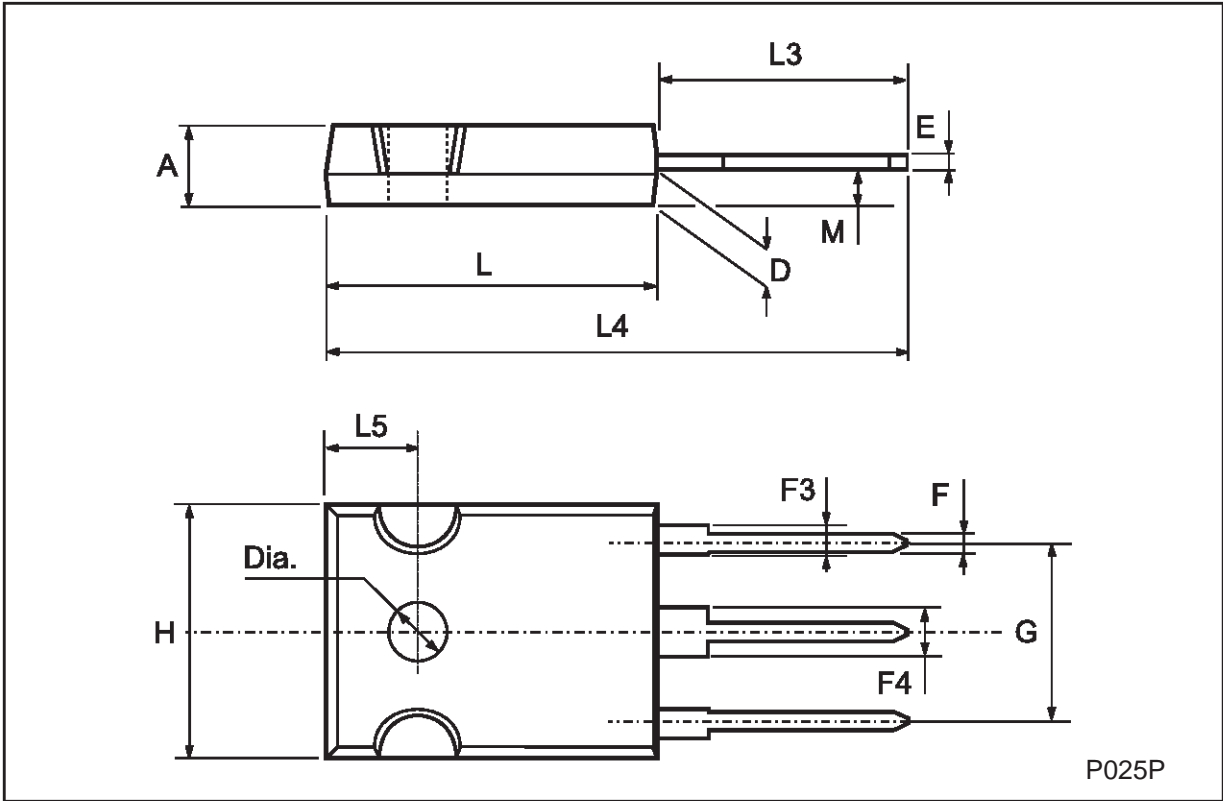


Fig. 3 Switching Waveforms



**TO-247 MECHANICAL DATA**

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.7		5.3	0.185		0.209
D	2.2		2.6	0.087		0.102
E	0.4		0.8	0.016		0.031
F	1		1.4	0.039		0.055
F3	2		2.4	0.079		0.094
F4	3		3.4	0.118		0.134
G		10.9			0.429	
H	15.3		15.9	0.602		0.626
L	19.7		20.3	0.776		0.779
L3	14.2		14.8	0.559		0.582
L4		34.6			1.362	
L5		5.5			0.217	
M	2		3	0.079		0.118



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